

SOT1437-1

plastic small outline package; 10 leads; body width 3.9 mm;
body thickness 1.35 mm

25 August 2016

Package information

1. Package summary

Dimensions (mm)	6.2 x 3.9 x 1.75
Terminal position code	D
Package type descriptive code	SO10
Package outline version code	SOT1437-1
Manufacturer package code	SOT1437
Package type industry code	SO10
Package outline version description	plastic small outline package; 10 leads; body width 3.9 mm; body thickness 1.35 mm
Package style descriptive code	SO
Package body material type	P
Mounting method type	S
Package life cycle status	REL
Security status	COMPANY PUBLIC
Issue date	6-3-2015
Customer specific indicator	N
Maturity	Product

Table 1. Package summary

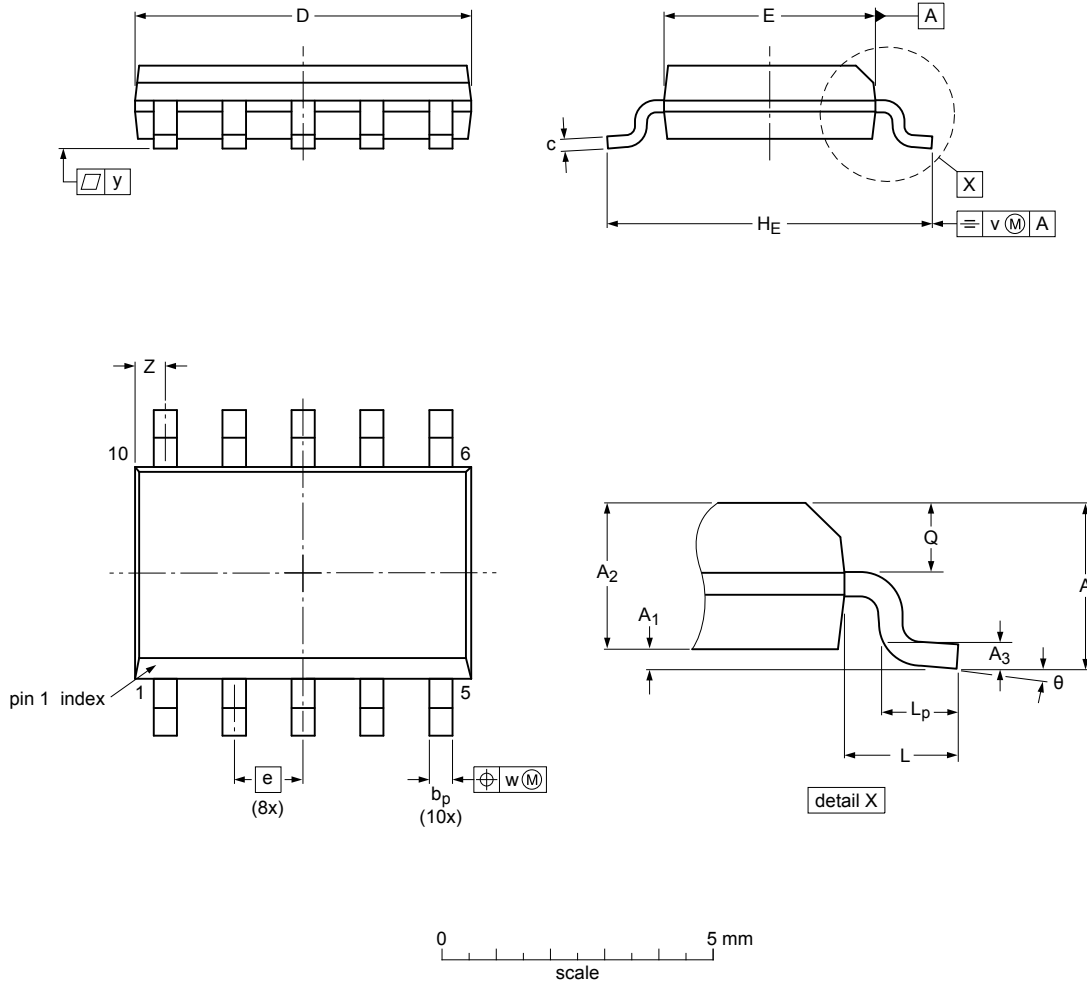
Symbol	Parameter	Min	Typ	Nom	Max	Unit
A ₂	package height	1.25	-	1.35	1.45	m
A	seated height	-	-	-	1.75	mm
D	package length	6.1	-	6.2	6.3	m
E	package width	3.8	-	3.9	4	m
e	nominal pitch	-	-	1.27	-	m
n ₂	actual quantity of termination	-	-	10	-	



2. Package outline

SO10: plastic small outline package; 10 leads; body width 3.9 mm; body thickness 1.35 mm

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Dimensions

Unit	A	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	Z	θ
max	1.75	0.25	1.45		0.49	0.25	6.3	4.0		6.20		1.00	0.70				0.70	8°
nom		0.18	1.35	0.25	0.43	0.22	6.2	3.9	1.27	6.00	1.05	0.70	0.65	0.25	0.25	0.1	0.56	4°
min		0.10	1.25		0.36	0.19	6.1	3.8		5.80		0.40	0.60				0.30	0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

so11437-1_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1437-1					15-02-09- 15-03-06

Fig. 1. Package outline SO10 (SOT1437-1)

3. Legal information

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